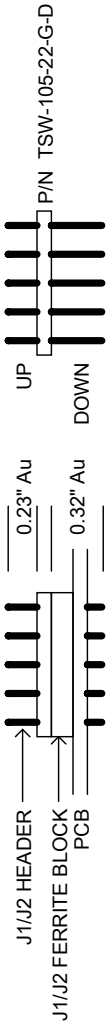
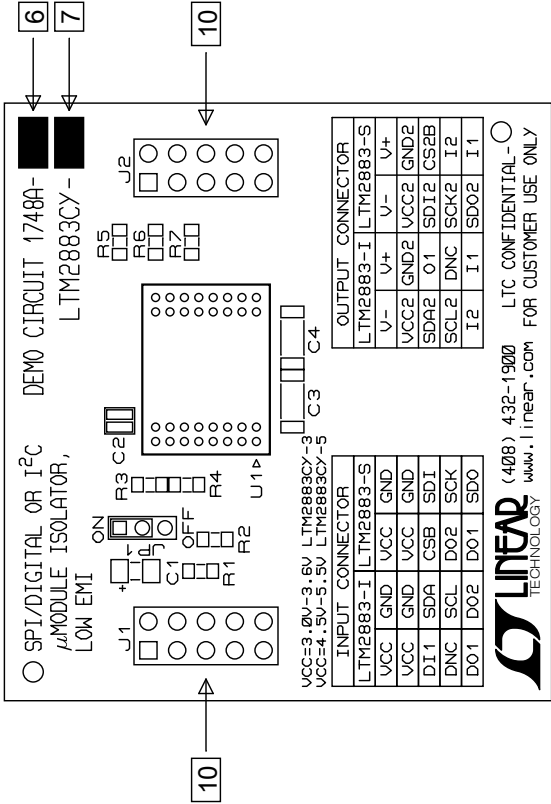


REVISION HISTORY				
ECO	REV	DESCRIPTION	APPROVED	DATE
-	1	1ST PROTOTYPE	KEITH B.	08-16-10

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610
- 2. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELCIUS
- 3. DEPANALIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD
- 4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
- 5. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD
- 6. MARK ASSEMBLY TYPE WITH BLACK PERMANENT MARKER WHERE SHOWN
- 7. MARK IC PART NUMBER WITH BLACK PERMANENT MARKER WHERE SHOWN
- 8. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD
- 9. INSTALL SHUNTS AS SHOWN

10. PLACE FERRITE BLOCK ON LONG SIDE HEADER PINS BEFORE BOARD INSERTION



P/N 2644247101

APPROVALS		LTC CONFIDENTIAL FOR CUSTOMER USE ONLY	
PCB DES.	KEITH B.	1630 McCarthy Blvd. Milpitas, CA 95035 Phone: (408) 432-1900 Fax: (408) 434-0507 www.linear.com	
APP ENG.	KEITH B.		
TITLE: SCHEMATIC		SPI/DIGITAL OR I2C uMODULE ISOLATOR, LOW EMI	
SCALE = 1.5:1		REV. 1	
DATE: Monday August 16, 2010		SHEET 1 OF 1	